CHIPQUIK®

JET551SNL10T5

Datasheet revision 1.1 www.chipquik.com

Jet Printing Solder Paste Sn96.5/Ag3.0/Cu0.5 T5 Vacuum Mixed 10cc/35g Syringe

Product Highlights

Chip Quik® Jet Printing Solder Paste Optimized for Jet Printing Applications (Vacuum Mixed) Higher Activity No-Clean, Better Wetting Printing speeds up to 100mm/sec Long stencil life

Clear residue Low voiding Excellent wetting compatibility on most board finishes Dispense grade Compatible with enclosed print heads **RoHS 3 and REACH compliant**

Specifications

Wide process window

Alloy: Sn96.5/Ag3.0/Cu0.5

Mesh Size: T5 Micron (µm) Range: 15-25

Flux Type: Synthetic No-Clean

Flux Classification: ROL0

Metal Load: 84% Metal by Weight, Vacuum Mixed

217-220°C (423-428°F) Melting Point: Packaging: 10cc/35a Syringe

Refrigerated >12 months, Unrefrigerated >6 months *See notes below: Shelf Life:

<u>*Shelf Life Notes:</u> Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R&D testing purposes.

Printer Operation

Print Speed: 25-100mm/sec

Squeegee Pressure: 70-250g/cm of blade

Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F) >4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Refrigerate at 3-8°C (37-46°F). Do not freeze. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

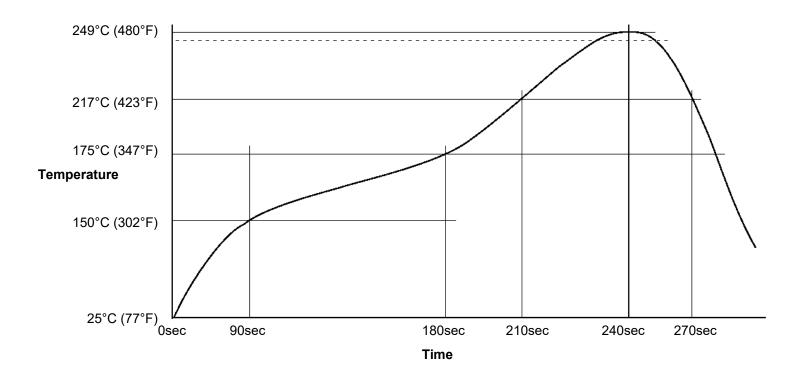
Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

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Recommended Profile

Reflow profile for Sn96.5/Ag3.0/Cu0.5 solder assembly, designed as a starting point for process optimization.



Test Results

rest results		
Test J-STD-004 or other	Test Requirement	Result
requirements as stated		
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C,	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
85% RH @ 168 Hours		
Tack Value	IPC-TM-650: 2.4.44	50-55g
Viscosity – Malcom @ 10 RPM/25°C (x10³mPa/s)	IPC-TM-650: 2.4.34.4	Print: 160-220, Dispense: 90-120
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes